



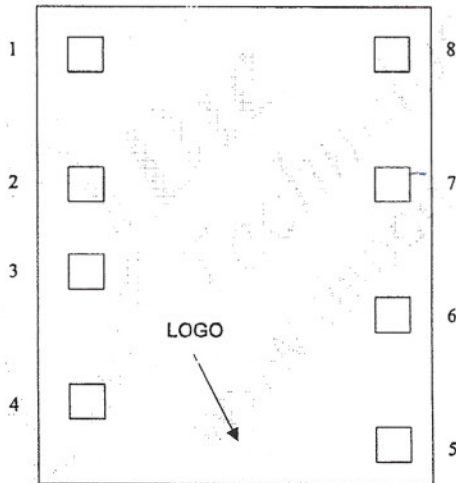
Sierra Components, Inc.

2222 Park Place • Suite 3E • Minden, Nevada 89423
 Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

PAD FUNCTIONS

- 1 NOT CS
- 2 SO
- 3 NOT WP
- 4 GND
- 5 SI
- 6 SCK
- 7 NOT HOLD
- 8 VCC



Topside Metal: Aluminum
Backside Metal: Silicon
Backside Potential:
Bond Pad Size: ..004" Min.
Mask Ref: C18A

MFG: ISSI Semiconductor

THICKNESS: .019"

Part # IS25C01

APPROVED BY: R Bacon

DIE SIZE : .035"x .045"

DATE: 9/23/09